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DATE: Thursday, March 11, 2004

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| <input type="checkbox"/> | L1 | (semiconductor or semiconductor or semi-conductor or semi-conductor or computerchip or computer-chip or (computer near2 chip)).clm. | 123905 |
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END OF SEARCH HISTORY

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1. 6669783. 28 Jun 01; 30 Dec 03. High temperature electrostatic chuck. Sexton; Greg, et al. 118/728; 118/725 156/345.51 156/345.52 361/234. H01L021/306 C23C016/00.
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2. 6653212. 09 Apr 01; 25 Nov 03. Method and apparatus for thin-film deposition, and method of manufacturing thin-film semiconductor device. Yamanaka; Hideo, et al. 438/485; 118/723VE 118/724 438/788 438/903. H01L021/20 C23C016/00.
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3. 6379988. 16 May 00; 30 Apr 02. Pre-release plastic packaging of MEMS and IMEMS devices. Peterson; Kenneth A., et al. 438/51; 257/E21.502 257/E21.504 257/E23.124 257/E23.129 438/106 438/115 438/116 438/125 438/55 438/64. H01L021/00 H01L021/44 H01L021/48.
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4. 6357385. 05 Oct 99; 19 Mar 02. Plasma device. Ohmi; Tadahiro, et al. 118/723AN; 118/723MW. C23C016/00.
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5. 6352593. 11 Aug 97; 05 Mar 02. Mini-batch process chamber. Brors; Daniel L., et al. 118/724; 118/641 118/725 118/730. C23C016/48.
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6. 6245202. 08 Oct 98; 12 Jun 01. Plasma treatment device. Edamura; Manabu, et al. 204/298.06; 118/723AN 118/723I 118/723IR 156/345.48 204/298.11 257/E21.218. C23C014/34.
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8. 6234219. 25 May 99; 22 May 01. Liner for use in processing chamber. Donohoe; Kevin G.. 141/98; 118/715 118/723I 118/723R 118/723VE 141/11 141/63 141/65 141/66 141/69 141/85 141/91. B65B001/04 B65B003/04 B67C003/02.
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9. 6217785. 09 Dec 96; 17 Apr 01. Scavenging fluorine in a planar inductively coupled plasma reactor. Collins; Kenneth S., et al. 216/68; 118/723I 156/345.48 438/723. H05H001/00 H01L021/00.
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10. 6150232. 05 Feb 99; 21 Nov 00. Formation of low k dielectric. Chan; Lap, et al. 438/421; 257/522 257/E21.581 438/422. H01L021/76.
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12. 5948704. 05 Jun 96; 07 Sep 99. High flow vacuum chamber including equipment modules such as a plasma generating source, vacuum pumping arrangement and/or cantilevered substrate support. Benjamin; Neil, et al. 438/715; 118/723R 118/725 118/728 118/733 156/345.51 216/67 216/68 216/69 279/128 427/569 427/570 427/571 427/573 427/575. H01L021/306 H01L021/3065 H05H001/00.
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14. 5805408. 22 Dec 95; 08 Sep 98. Electrostatic clamp with lip seal for clamping substrates. Maraschin; Robert, et al. 361/234;. H02N013/00.
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| Terms | Documents |
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| L9 and (seal\$ or oring\$ or o-ring\$ or gasket\$ or gaskit\$ or block\$).clm. | 24 |

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First Hit Fwd Refs

L10: Entry 1 of 24

File: USPT

Dec 30, 2003

US-PAT-NO: 6669783

DOCUMENT-IDENTIFIER: US 6669783 B2

TITLE: High temperature electrostatic chuck

DATE-ISSUED: December 30, 2003

INVENTOR-INFORMATION:

| NAME | CITY | STATE | ZIP CODE | COUNTRY |
|---------------------|------------|-------|----------|---------|
| Sexton; Greg | Fremont | CA | | |
| Schoepp; Alan | Ben Lomond | CA | | |
| Kennard; Mark Allen | Pleasanton | CA | | |

ASSIGNEE-INFORMATION:

| NAME | CITY | STATE | ZIP CODE | COUNTRY | TYPE CODE |
|--------------------------|---------|-------|----------|---------|-----------|
| Lam Research Corporation | Fremont | CA | | | 02 |

APPL-NO: 09/ 892458 [PALM]

DATE FILED: June 28, 2001

INT-CL: [07] H01 L 21/306, C23 C 16/00

US-CL-ISSUED: 118/728; 361/234, 156/345.51, 156/345.52, 118/725

US-CL-CURRENT: 118/728; 118/725, 156/345.51, 156/345.52, 361/234

FIELD-OF-SEARCH: 361/234, 156/345.53, 118/728, 118/725

PRIOR-ART-DISCLOSED:

U.S. PATENT DOCUMENTS

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| <input type="checkbox"/> <u>4340462</u> | July 1982 | Koch | |
| <input type="checkbox"/> <u>4534816</u> | August 1985 | Chen et al. | |
| <input type="checkbox"/> <u>4579618</u> | April 1986 | Celestino et al. | |
| <input type="checkbox"/> <u>4615755</u> | October 1986 | Tracy et al. | |
| <input type="checkbox"/> <u>4665463</u> | May 1987 | Ward et al. | |
| <input type="checkbox"/> <u>4692836</u> | September 1987 | Suzuki | |
| <input type="checkbox"/> <u>4948458</u> | August 1990 | Ogle | |
| <input type="checkbox"/> <u>5055964</u> | October 1991 | Logan et al. | |